

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: **Uwe Schwarz**

Serial No: **10/537,211**

I.A. Filing Date: **December 5, 2003**

For: **Production of Microelectromechanical Systems (MEMS)  
Using the High-Temperature Silicon Fusion Bonding  
of Wafers (as corrected herewith)**

**PRELIMINARY AMENDMENT**

**Introductory Comments**

Dear Sir:

Please amend the application as follows.

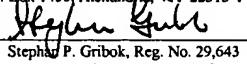
**Amendments to the Specification** begin on page 2 of this Amendment.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this Amendment. These amended claims shall replace the claims contained in the English translation of the application as submitted herewith.

**Remarks** begin on page 6 of this Amendment.

**CERTIFICATE OF MAILING,  
37 C.F.R. §1.8(a)**

I certify that this correspondence and the enclosures mentioned therein are being deposited by First Class U.S. Mail with sufficient postage on the date shown below, addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

  
Stephen P. Gribok, Reg. No. 29,643

3-16-2006

Date